InCarrier Loader plus

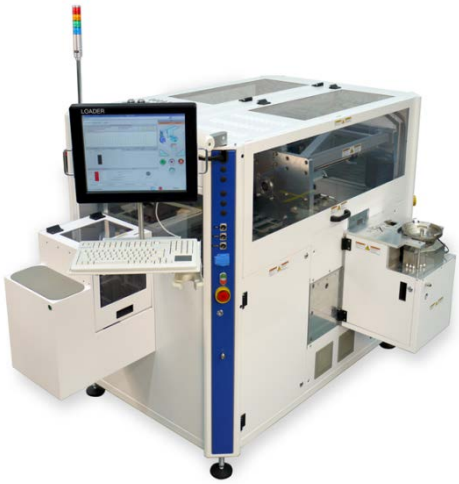
High Speed Loading for Test in Carriers

Supported Media

- JEDEC tray
- bulk
- plastic tube

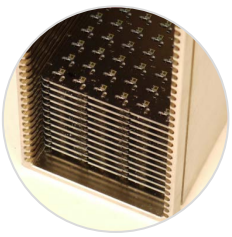
Facts

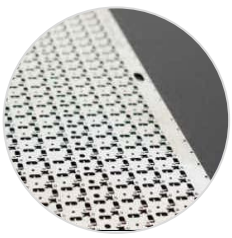
- high speed loading into Multitest InCarrier trays
- flexible line set up with Multitest InStrip and production-defined unloading equipment
- standard SEMI mapping interface G84 or E142
- integrated loading quality control
- carrier damage control



Solution for

- leaded and leadless devices
- all SO, QFN and BGA packages





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InCarrier Loader plus

High Speed Loading for Test in Carriers

1 Base System

1.1 Loader for Multitest InCarriers
- Stand-alone equipment
- User Interface: Display with 21.5” Touch Screen

1.2 Available Loading modules
- Auto Tray Loader (max. capacity: 30 JEDEC trays)
- Bowl Feeder (max device size: 5x5 mm)
- Tube Loader

1.3 Host interface
- SECS GEM G84 or file based map handling

1.4 Options
- +/- 90° rotation for pin 1 orientation
- InSite connection
- Bar code lot ID reader
- Closed loop ionizer
- Ground fault monitoring
- on request
- …

2. Carriers / Packages

2.1 Carrier size
- Min: 215 x 63 mm
- Max: 268 x 98 mm

2.2 Device types
- QFN, WLP, SO, BGA, SOT, CSP, LGA
- Package thickness: max. 6 mm

3. Conversion

3.1 Package Style Conversion
- Conversion time dependent on Input Modules
  - tray < 30 min
  - bowl < 3 hrs
  - tube < 3 hrs
- Only 1 person necessary

3.2 Adjustment/ Calibration after Conversion
- The system provides semi-automatic adjustment

4. Operations and Checks

4.1 Operator Access
- Accessible form front and right side

4.2 Slotted Magazine Loader
- Single Slotted Cassette Loader for cassettes with 235 mm max. height

4.3 Carrier Inspections
- Pocket empty inspection (incoming carrier)
- Spring damage inspection (incoming carrier)
- Clamping inspection of devices (outgoing carrier)

4.4 Carrier Traceability
- Dot Matrix Code (ECC 200) on Carrier

5. Performance

5.1 Throughput
- Up to 16,000 uph @ carriers with 144 or more devices
- Throughput might be limited by input medium (e.g. Manual Tube Operation)

5.2 Jam Rate
- 1/8000 devices (typically)

6. Facility requirements

6.1 Voltage
- 3 x 208 – 480 V, 50-60 Hz

6.2 Compressed air
- 5 – 10 bar

6.3 Vacuum
- External vacuum or internal vacuum pump (option)

6.4 System dimension (WxDxH) (w/o signal tower)
- Tube, Bowl: 2.2 x 1.62 x 1.55 m
- Tray: 2.2 x 1.14 x 1.55 m

6.5 System weight
- 1000 kg

7. Compliance and Standards

7.1 Compliant to
- CE
- Machine Directive 98/37/EC
- Low Voltage Directive 73/23/EEC
- Electromagnetic Compatibility Directive 89/336/EEC

7.2 Strip Mapping Interface
- SEMI standard SECS/GEM G84 or E142

7.3 Clean Room Requirements
- Class 8 semiconductor testing area

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